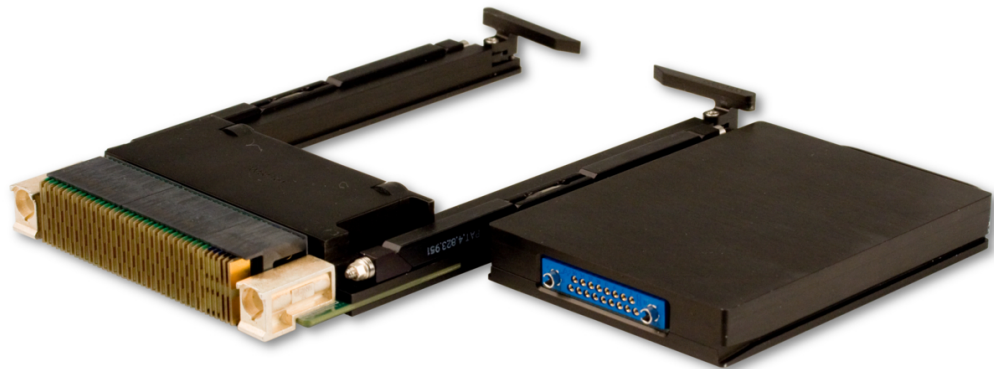


# XPort6170

## 3U VPX Removable SATA Solid State Drive (SSD) Carrier

- ▶ Module carrier fits within a standard 3U VPX slot
- ▶ SATA backplane interface over P1
- ▶ -40°C to 85°C operating temperature range
- ▶ High-reliability 100,000 life cycle connector
- ▶ Easy insertion and extraction mechanism
- ▶ Designed for rugged environments
- ▶ Up to 256 GB of storage with the XPort6192 removable module



### XPort6170

The XPort6170 3U VPX removable module carrier has been designed from the ground up to meet today's ruggedized storage requirements. By utilizing X-ES solid-state NAND flash module technology, the XPort6170 provides a high-performance, high-density, reliable removable VPX memory solution. The XPort6170 is capable of operating within the demanding environments of MIL-STD-810F, including harsh temperatures from -40°C to 85°C as well as rigorous shock and vibration conditions.

Complementing the XPort6170 module carrier and designed with an extremely high-reliability connector, the XPort6192 SSD storage module will support up to 100,000 insertions and extractions. The use of SLC NAND flash components allows the XPort6192 to support least 100,000 program erase cycles. Depending on the application, the life expectancy can be increased with the utilization of the XPort6192's internal global wear leveling algorithms.

The combination of XPort6170 VPX carrier and XPort6192 SSD module provides the next generation of ruggedized removable media.

# X-ES

Extreme Engineering Solutions

*...Always Fast*

### Extreme Engineering Solutions

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**VPX (VITA 46) P0 I/O**

- I<sup>2</sup>C port

**VPX (VITA 46) P1 I/O**

- One SATA port

**Physical Characteristics**

- 3U VPX-REDI conduction- or air-cooled form factor
- Dimensions: 100 mm x 160 mm

**XPort6192 SSD storage module**

- Serial ATA (SATA) Rev 2.6 compliant
- 240 MB/s sustained read
- 215 MB/s sustained write
- 100,000 insertions and extractions
- 100,000 program and erase cycles
- Less than 2 W maximum power dissipation
- Up to 256 GB density

**Environmental Requirements**

- Contact factory for appropriate board configuration based on environmental requirements.
- Supported ruggedization levels (see chart below): 1, 3, 5
  - Conformal coating available as an ordering option

Supported Ruggedization Level	Level 1	Level 3	Level 5
Cooling Method	Standard Air-Cooled	Rugged Air-Cooled	Conduction-Cooled
Operating Temperature	0 to +55 °C ambient (300 LFM)	-40 to +70 °C (600 LFM)	-40 to +85 °C (board rail surface)
Storage Temperature	0 to +85 °C ambient	-40 to +105 °C ambient	-55 to +105 °C ambient
Vibration	0.002 g <sup>2</sup> /Hz, 5 to 2000 Hz	0.04 g <sup>2</sup> /Hz (maximum), 5 to 2000 Hz	0.1 g <sup>2</sup> /Hz (maximum), 5 to 2000 Hz
Shock	20 g, 11 ms sawtooth	30 g, 11 ms sawtooth	40 g, 11 ms sawtooth
Humidity	0% to 95% non-condensing	0% to 95% non-condensing	0% to 95% non-condensing

